ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and F	position De IPC, Bannockt an-American co	c laration ourn, Illinois. A opyright conve	All rights reserved untions.	nder both	This docume level parts, th	ent is a declaration er	on of the substance acompasses all lo	es within the man wer level materia	nufacturer liste ls for which th	ed item. Note: if le manufacturer	the item is an a has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard For			Form Type Distribute					Materials and	rials and Mfg Information			
upplier Information													
ompany name*	Company un	Company unique ID			Unique ID Authority				Response Date*				
onsemi										2024-05-21			
Contact Name Title - C			itle - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards P			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title			Title - Representative			Phone - Representative*			Ema	Email - Representative*			
roduct-Env-Stewards	Product Enviro Compliance				NA			Proc	Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	FNB340	FNB34060T IPM SP		PM SPM3V 600V 40A		2024-05-21		СРА		15120.577	mg	Each	
Ianufacturing Proccess Inform	ation					•	-					·	
Terminal Plating / Grid Array I	Terminal Plating / Grid Array Material Terminal Base .		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature Max Tin		ture Max Time	at Peak Tempo	erature Numbe	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30	se	conds 3				
omments													
or more information regarding materi	al composition	please refer to	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
DBC	2416.55	mg	Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		966.6201	mg
			В	Nickel (Ni)	7440-02-0		24.1655	mg
			Supplier	Copper (Cu)	7440-50-8		1425.7645	mg
Die	52.1228	mg	Supplier	Silicon (Si)	7440-21-3		52.1228	mg
Die Attach	21.549	mg	Supplier	Silver (Ag)	7440-22-4		0.6465	mg
			Supplier	Tin (Sn)	7440-31-5		20.7948	mg
			Supplier	Copper (Cu)	7440-50-8		0.1077	mg
Die Attach Epoxy	1.34901	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.0405	mg
			Supplier	Silver (Ag)	7440-22-4		1.1467	mg
			Supplier	Proprietary	Proprietary Data		0.0675	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0944	mg
Die Attach Solder	1.07957	mg	Supplier	Silver (Ag)	7440-22-4		0.027	mg
			А	Lead (Pb)	7439-92-1	7a	0.9986	mg
			Supplier	Tin (Sn)	7440-31-5		0.054	mg
Lead Frame	3026.94	mg	Supplier	Silver (Ag)	7440-22-4		0.0303	mg
			Supplier	Iron (Fe)	7439-89-6		3.0269	mg
			Supplier	Copper (Cu)	7440-50-8		3022.9746	mg
			Supplier	Phosphorus (P)	7723-14-0		0.9081	mg
Mold Compound-Black	9436.02	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		471.801	mg
			Supplier	Carbon Black (C)	1333-86-4		94.3602	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		8398.0576	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		471.801	mg
lating	113.724	mg	Supplier	Tin (Sn)	7440-31-5		113.724	mg
Wire Bond - Al	50.409	mg	Supplier	Aluminum (Al)	7429-90-5		50.409	mg
Wire Bond - Cu	0.83371	mg	Supplier	Copper (Cu)	7440-50-8		0.8337	mg